

Title (en)  
THE METHOD OF MANUFACTURING A WIRE FROM CU-AL-MN-NI-FE ALLOY, ESPECIALLY FOR THE USE IN ADDITIVE MANUFACTURING

Title (de)  
VERFAHREN ZUM HERSTELLEN EINES DRAHTES AUS EINER CU-AL-MN-HALB-LEGIERUNG, INSBESONDERE FÜR DIE VERWENDUNG IN DER GENERATIVEN FERTIGUNG

Title (fr)  
PROCÉDÉ DE FABRICATION D'UN FIL À PARTIR D'UN ALLIAGE CU-AL-MN-NI-FE, EN PARTICULIER POUR L'UTILISATION DANS UNE FABRICATION ADDITIVE

Publication  
**EP 4060065 A1 20220921 (EN)**

Application  
**EP 21000358 A 20211216**

Priority  
PL 43730421 A 20210315

Abstract (en)  
The method of manufacturing a wire from Cu-Al -Mn-Ni-Fe alloy conducted by a multi-stage heat treatment in a protective atmosphere characterized in that after annealing at the temperature of 700-800 °C annealing of the semi-finished product at the temperature of 450-750 °C for 45 - 60 minutes is conducted, then it is etched in a pickling bath at the temperature of 50-60 °C for 50-60 minutes, and next it is rinsed and cleaned.

IPC 8 full level  
**C22C 9/01** (2006.01); **C22F 1/08** (2006.01); **C23G 1/10** (2006.01); **C23G 3/02** (2006.01)

CPC (source: EP PL)  
**B21C 37/047** (2013.01 - PL); **C22C 9/01** (2013.01 - EP PL); **C22C 9/05** (2013.01 - PL); **C22C 9/06** (2013.01 - PL); **C22F 1/08** (2013.01 - EP); **C23G 1/103** (2013.01 - EP); **C23G 3/021** (2013.01 - EP)

Citation (applicant)  
US 3942582 A 19760309 - DOMPAS JOHN M, et al

Citation (search report)

- [Y] CN 111424190 A 20200717 - XINHUA HEANSHENG ELECTRONIC TECH CO LTD
- [Y] CN 107099804 A 20170829 - NANJING INST TECH
- [A] CN 109266874 A 20190125 - HENAN DALUN ELECTRONIC TECH CO LTD
- [T] "Metals Handbook Desk Edition", 31 December 1998, ASM INTERNATIONAL, ISBN: 978-1-62708-199-3, article DAVIES JOSEPH: "Surface Cleaning", pages: 1126 - 1135, XP055923820, DOI: 10.31399/asm.hb.mhde2.a0003213

Designated contracting state (EPC)  
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)  
BA ME

DOCDB simple family (publication)  
**EP 4060065 A1 20220921**; PL 242160 B1 20230123; PL 437304 A1 20220919

DOCDB simple family (application)  
**EP 21000358 A 20211216**; PL 43730421 A 20210315